

TRU

CF<sub>4</sub>/O<sub>2</sub>/N<sub>2</sub>

### Uranium Dioxide Reaction in a Ternary CF<sub>4</sub>/O<sub>2</sub>/N<sub>2</sub> Plasma Gas for the TRU Decontamination Application

17

150

CF<sub>4</sub>/O<sub>2</sub> (UO<sub>2</sub>) N<sub>2</sub> 가

CF<sub>4</sub>/O<sub>2</sub>/N<sub>2</sub> R.F.(Radio Frequency) . CF<sub>4</sub>

O<sub>2</sub> 4 : 1 , N<sub>2</sub>

가 N<sub>2</sub> CF<sub>4</sub>/O<sub>2</sub> 5% 가 가 , 가

. R.F. 가 .

(OES, Optical Emission Spectroscopy)

N<sub>2</sub> 5% 가 가 CF<sub>4</sub>/O<sub>2</sub>

2 가 , R.F. 가 .

## Abstract

To advance the reaction rate of  $\text{UO}_2$  with  $\text{CF}_4/\text{O}_2$  R.F. plasma, experiments with  $\text{N}_2$  added  $\text{CF}_4/\text{O}_2$  plasma under R.F. power were carried out. Along with those experiments by intermittent weight loss measurements, an optical study is investigated. In this study, experimental variables are the ratio of  $\text{N}_2$  to  $\text{CF}_4/\text{O}_2$  gas, substrate temperature, and plasma power. The ratio,  $\text{CF}_4/\text{O}_2$ , is maintained to be four since it is reported to be the optimum in the binary gas mixture system for  $\text{UO}_2$  etching process. It is found that when small amount of  $\text{N}_2$  is added to  $\text{CF}_4/\text{O}_2$  plasma, the etching rate can be enhanced almost twice compared to that of  $\text{CF}_4/\text{O}_2$  plasma without  $\text{N}_2$  gas. And it is proportional to plasma power and substrate temperature. Optical emission spectra focused on the fluorine density is thoroughly analyzed to support the results since the fluorine atom plays a significant role in the chemical etching of  $\text{UO}_2$  in the mixture gas plasma. It revealed that the fluorine atom density reaches a maximum at the optimized  $\text{N}_2/\text{CF}_4/\text{O}_2$  plasma, regardless of the R.F. power and temperature, and the etching rate of  $\text{UO}_2$  is closely proportional to the fluorine atom density.

### I.

~ 1.5wt% 가

1,2), (TRU, transuranic elements)가 가  
(PUREX, plutonium uranium reduction extraction process)  
3,4), TRU

2

TRU  
0.1%

5),

가

4:1

$\text{CF}_4/\text{O}_2$

$\text{N}_2$

가

가  $\text{CF}_4:\text{O}_2 =$

(OES)

F

II.

CF<sub>4</sub>/O<sub>2</sub> N<sub>2</sub> 가  
, CF<sub>4</sub>/O<sub>2</sub>/N<sub>2</sub> R.F.  
가  
1 2  
(OES,  
optical emission spectroscopy, Ocean Optics, Inc.)  
3 가  
(mass flow controller, MKS) 13.56 MHz R.F.  
가  
3mm (thermocouple)가  
16 liter  
10cm 가 가 , (rotary pump) 10<sup>-3</sup> Torr ,  
(diffusion pump) 10<sup>-6</sup> Torr  
800 가 R.F. 600 W  
CF<sub>4</sub>, O<sub>2</sub> N<sub>2</sub> 가 99.999% 0.5  
sccm (standard cc per minute) 100sccm  
가  
(low speed diamond  
saw) 0.35mm 가 600  
가  
200 20 가  
10<sup>-5</sup> g 가 (BP 210 D, Sartorius)  
1.6×10<sup>-6</sup> Torr 200  
baking CF<sub>4</sub>/O<sub>2</sub>/N<sub>2</sub>  
CF<sub>4</sub> O<sub>2</sub> 40 sccm 10 sccm 4 : 1 0.3  
Torr 0 ~ 6 sccm N<sub>2</sub> 가 R.F. 50 ~200 W 가

60

CF<sub>4</sub>/O<sub>2</sub>

가 CF<sub>4</sub> O<sub>2</sub>

가 N<sub>2</sub> 가

etchant

R.F. 100 W

Ocean Optics

OOIBase Operating Software

### III.

CF<sub>4</sub> O<sub>2</sub>

<sup>5)</sup> CF<sub>4</sub>/O<sub>2</sub>

N<sub>2</sub> 가

<sup>4)</sup> CF<sub>4</sub>/O<sub>2</sub> 가 4

OES

R.F.

CF<sub>4</sub> O<sub>2</sub>

5 O<sub>2</sub> 가 20%

가

CF<sub>4</sub>/O<sub>2</sub>

가

, R.F.

monolayer

$$\text{Molecular Layer Etching Rate} = \frac{N_a / M}{(N_a \rho / M)^{2/3}} \frac{x}{A t} \text{ (monolayers/min)}$$

$x =$  (g),  $A =$  (cm<sup>2</sup>),  $t =$  (min)

$N_a = 6.022045 \times 10^{23}$  (/mol),  $\rho = 10.96$ (g/cm<sup>3</sup>),  $M = 270.03$ (g/mol)

6 R.F. 100 W, 300

CF<sub>4</sub> O<sub>2</sub> 50 sccm

N<sub>2</sub>

3 sccm 가 가 12 sccm 가 CF<sub>4</sub> O<sub>2</sub>

600 monolayers/min

100 W, 290 . N<sub>2</sub> 5% 가 가

1200 monolayers/min 가 N<sub>2</sub> 가

2 가 CF<sub>4</sub> O<sub>2</sub> N<sub>2</sub> 가

50 sccm CF<sub>4</sub> O<sub>2</sub> 4:1

N<sub>2</sub> 가 7 . 가

N<sub>2</sub> 5% 가 2 가 가

8 R.F. 가

R.F. CF<sub>4</sub> O<sub>2</sub> N<sub>2</sub> 가

N<sub>2</sub> 가 CF<sub>4</sub> O<sub>2</sub> 가

2 가 가 가 가 가

가가 N<sub>2</sub> 가

R.F. 가 , 9

가 가 2 가 가 .

가 10

가 5% 가 CF<sub>4</sub>/O<sub>2</sub> 2 가

IV.

CF<sub>4</sub>/O<sub>2</sub> 6)

CF<sub>4</sub> O<sub>2</sub> 3 N<sub>2</sub> CF<sub>4</sub>/O<sub>2</sub> 0 ~ 12 %

가 , N<sub>2</sub> 5% 가 2 가 가 , CF<sub>4</sub>/O<sub>2</sub>

150 W, 290 1000 monolayers/min ,

N<sub>2</sub> 가 2000 monolayers/min 가 .

(OES, Optical Emission Spectroscopy)

, N<sub>2</sub> 가 가 2 가

가가 . N<sub>2</sub> 가 ,

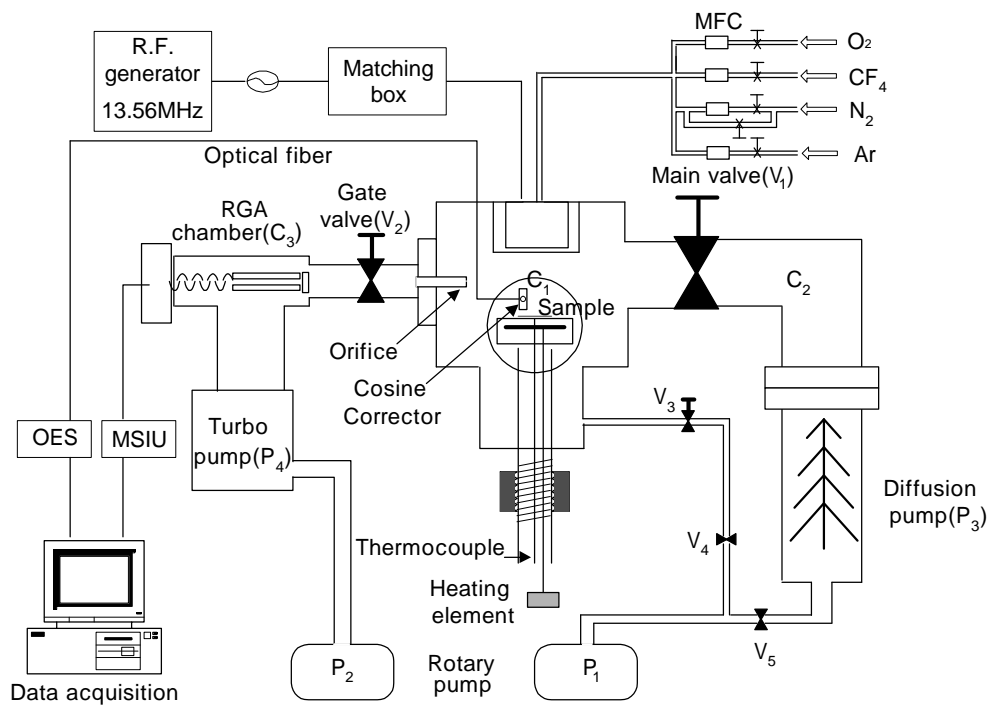
CF<sub>4</sub>/O<sub>2</sub> 가 R.F.

가  
 2 가 가 . N<sub>2</sub>  
 가 .  
 , N<sub>2</sub>  
 가 2 가 ,  
 .

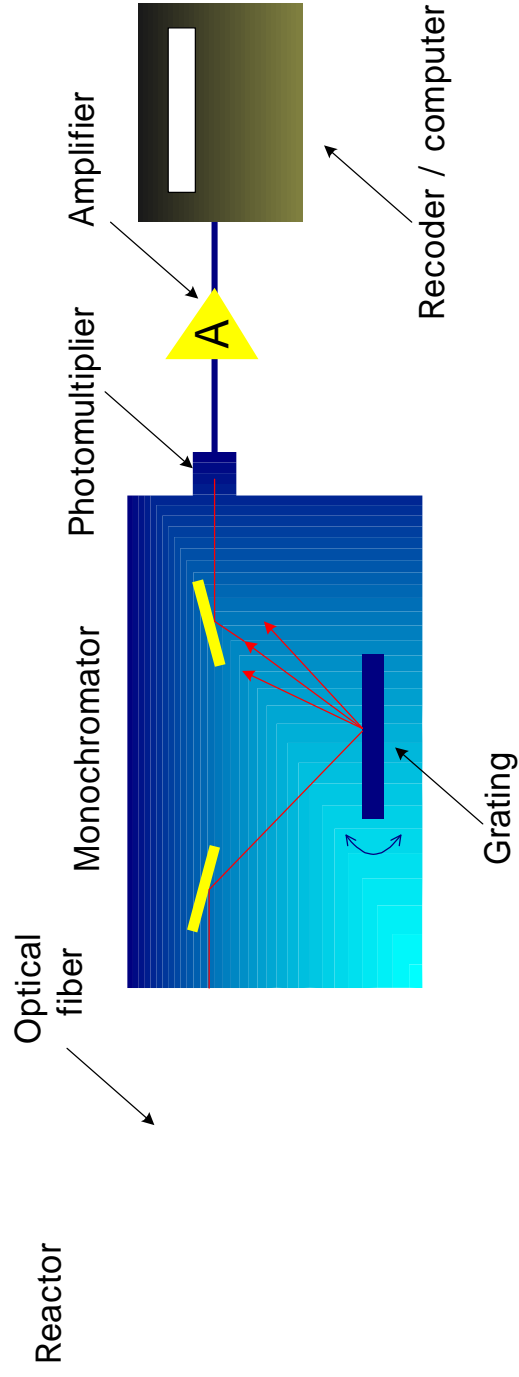
- 1) J. A. Partridge, R. E. Lerch, and G. P. Bosuego, *Decontamination of TRU Contaminated Metals*, HEDL-TC-1503, August (1979).
- 2) W. D. Bond, U. C. Mailen, and G. E. Michaels, *Evaluation of Methods for Decladding LWR Fuel for a Pyroprocessing-Based Reprocessing Plant*, ORNL/TM-12104 (1992).
- 3) P. A. Haas, D. D. Lee, and J. C. Mailen, *Reaction of Uranium Oxides with Chlorine and Carbon or Carbon Monoxide to Prepare Uranium Chlorides*, ORNL/TM-11792, November (1991).
- 4) J. J. Barghusen, A. A. Jonke, N. M. Levitz, M. J. Steindler, and R. C. Vogel, *Fluid-Bed Fluoride Volatility Processing of Spent Fuel Reactor Materials*, Progress in Nuclear Energy, Series III, Vol. 4, Process Chemistry, C. E. Stevenson, E. A. Mason, A. T. Gresky (eds.), Pergamon Press, (1970) 347.
- 5) J.W. Coburn, *IEEE Trans. on Plasma Science*, 19 (1991)1048.
- 6) Y. Kim, J. Min, K. Bae, and M. Yang, *Uranium Dioxide Reaction in CF<sub>4</sub>/O<sub>2</sub> RF Plasma*, J. Nucl. Mater., 270 (1999)253.



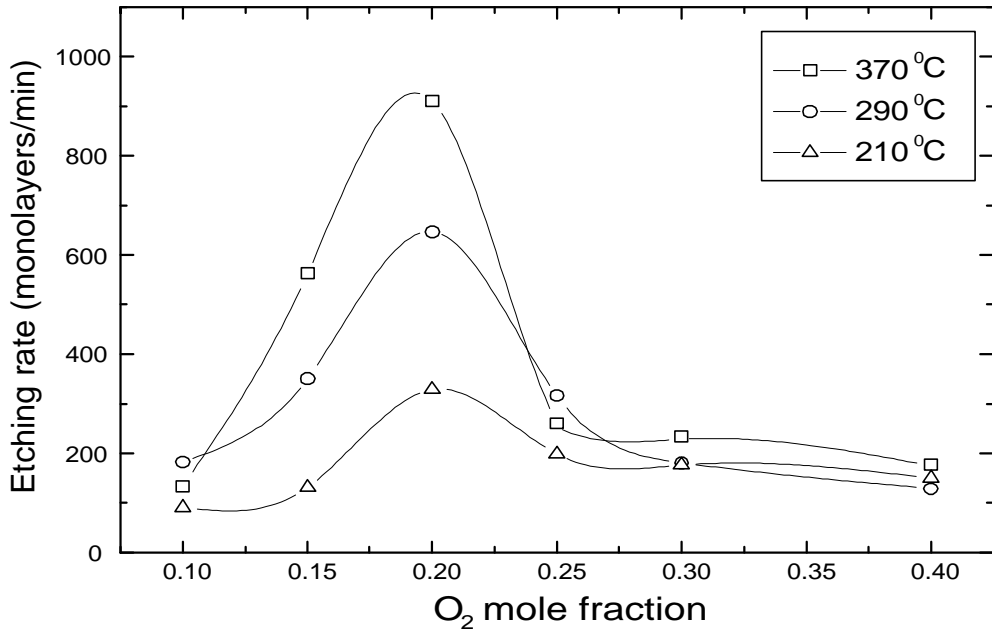
1



2

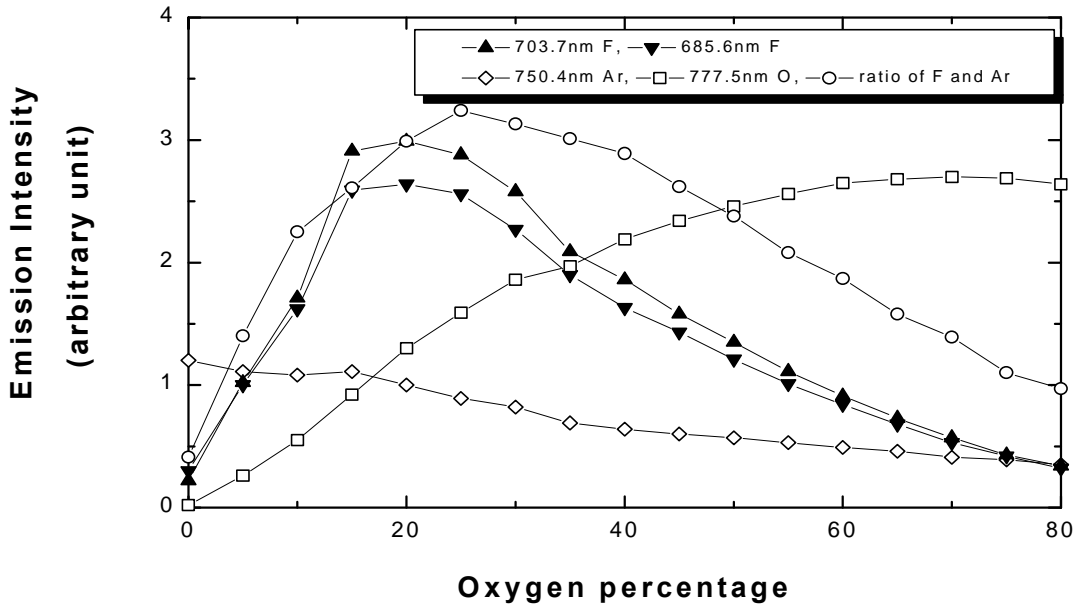






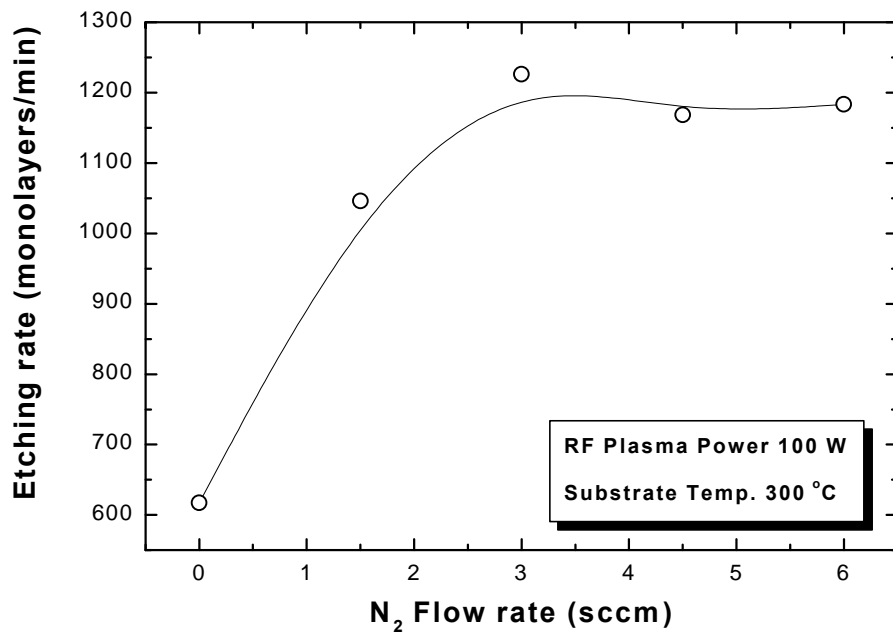
4<sup>6</sup> O<sub>2</sub>

(CF<sub>4</sub>/O<sub>2</sub> total flow rate: 50 sccm)



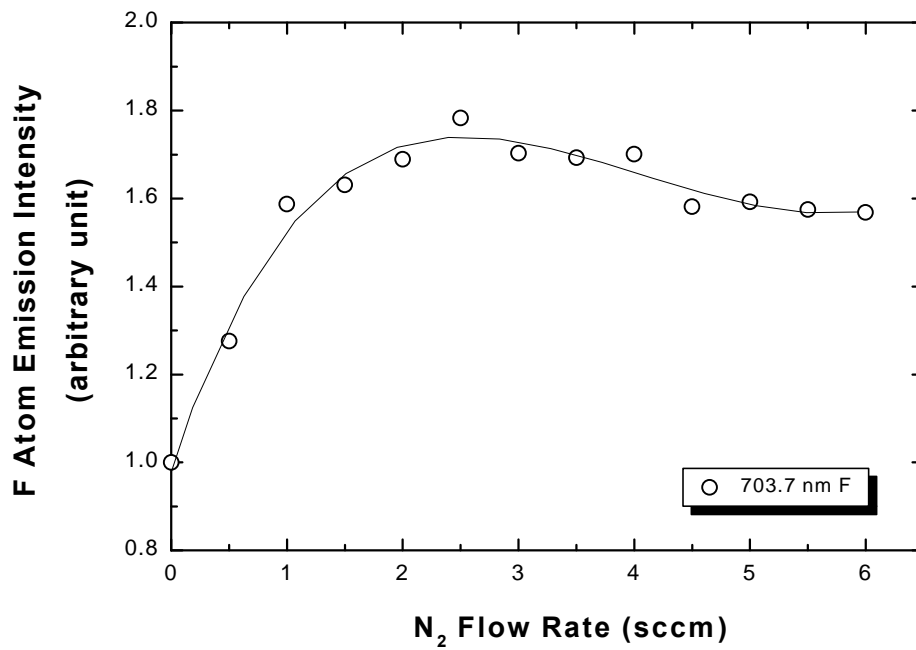
5 CF<sub>4</sub> O<sub>2</sub>

(total flow rate: 50 sccm, R.F. power: 100 W)



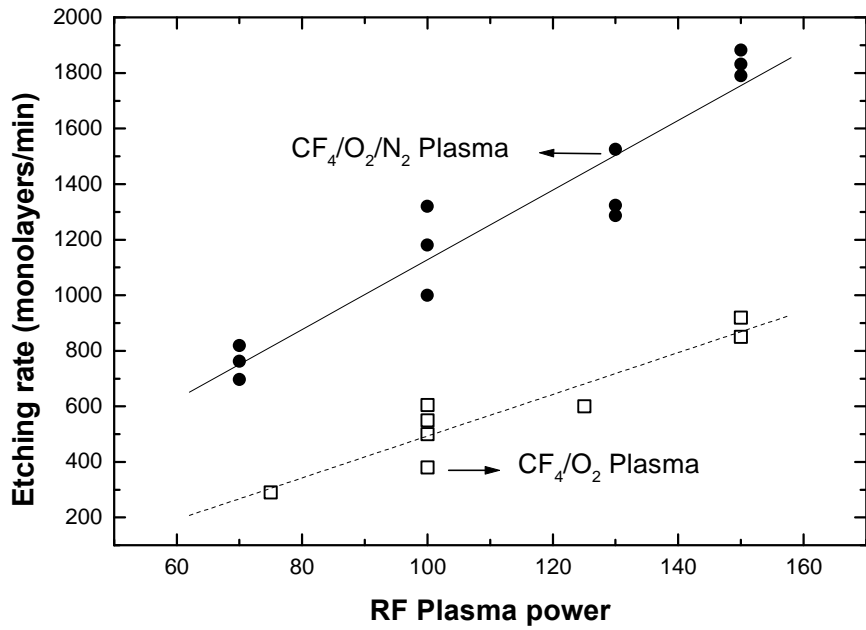
6

(CF<sub>4</sub>/O<sub>2</sub> flow rate: 50 sccm, reaction time 60 min)



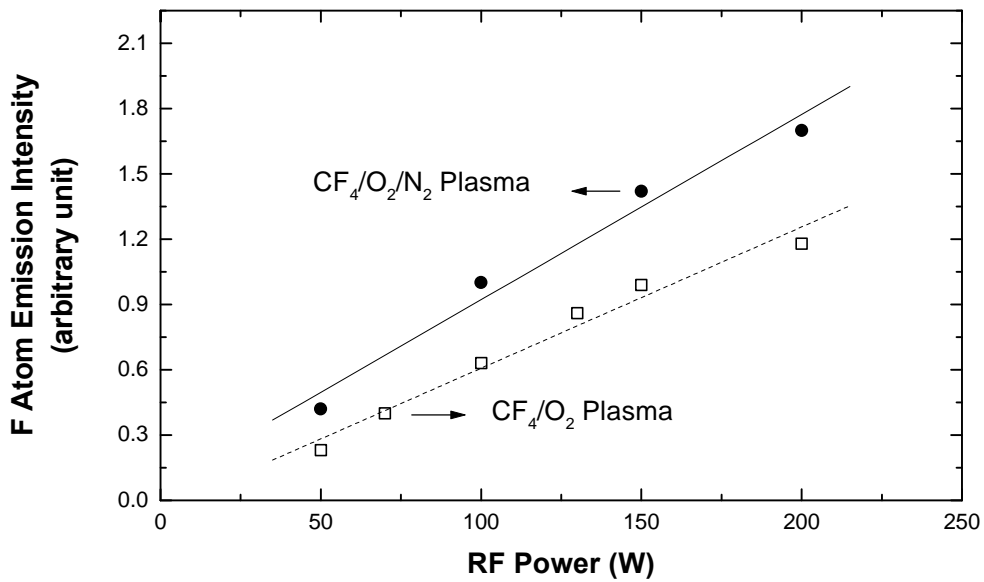
7 N<sub>2</sub> 가 CF<sub>4</sub> O<sub>2</sub>

(CF<sub>4</sub>/O<sub>2</sub> flow rate: 50 sccm, R.F. plasma power 100 W)



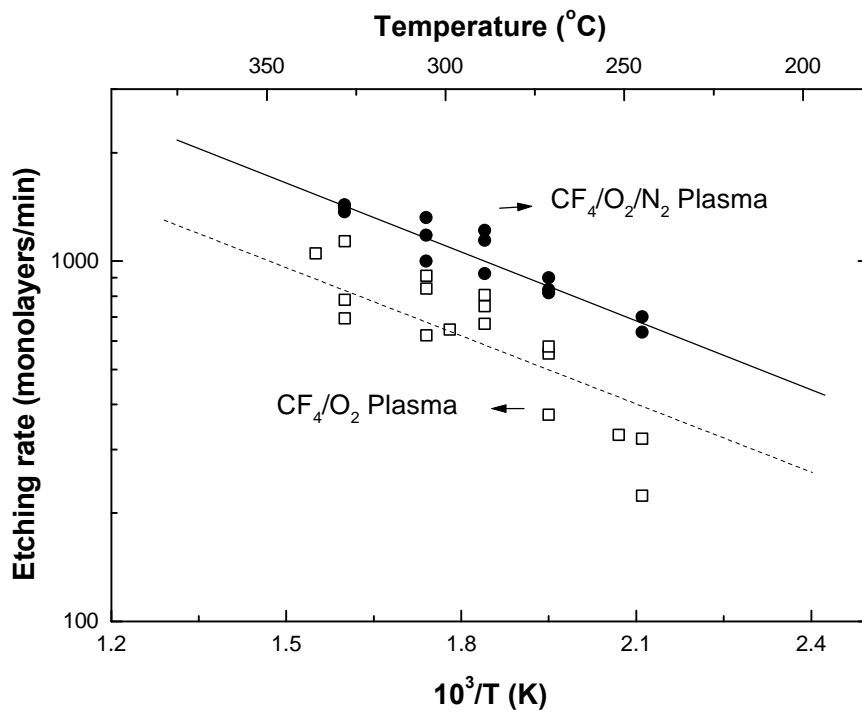
8 R.F.

( $\text{CF}_4/\text{O}_2$  flow rate: 50 sccm,  $\text{N}_2$  flow rate: 2.5 sccm, substrate temperature: 300 , reaction time: 60 min)



9 R.F.

( $\text{CF}_4/\text{O}_2$  flow rate: 50 sccm,  $\text{N}_2$  flow rate: 2.5 sccm)



10

( $CF_4/O_2$  flow rate: 50 sccm,  $N_2$  flow rate 2.5 sccm, R.F. plasma power 100 W, reaction time 60 min)